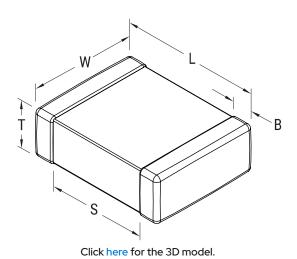




ESD SMD Comm X7R, Ceramic, 0.022 uF, 20%, 63 VDC, X7R, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II, 1206, 1.5 mm



| General Information | |
|--------------------------|---|
| Series | ESD SMD Comm X7R |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Electro Static Discharge, Class II |
| Features | Temperature Stable, Class II |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 17 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| 1206 |
|------------------|
| 3.2mm +/-0.2mm |
| 1.6mm +/-0.2mm |
| 0.78mm +/-0.10mm |
| 1.5mm MIN |
| 0.5mm +/-0.25mm |
| 1 |

| Specifications | |
|--|--|
| Capacitance | 0.022 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 20% |
| Voltage DC | 63 VDC |
| ESD Level per AEC-Q200 | 25,000 V ESD Level |
| Dielectric Withstanding Voltage | 157.5 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 45.4545 GOhms |

| Packaging Specifications | | |
|--------------------------|-----------|--|
| Packaging | Bulk, Bag | |
| Packaging Quantity | 1 | |

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